

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4277119

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ching-Wen Hung	07/02/2015
Wei-Cyuan Lo	07/02/2015
Ming-Jui Chen	07/02/2015
Chia-Lin Lu	07/02/2015
Jia-Rong Wu	07/02/2015
Yi-Hui Lee	07/02/2015
Ying-Cheng Liu	07/02/2015
Yi-Kuan Wu	07/02/2015
Chih-Sen Huang	07/02/2015
Yi-Wei Chen	07/02/2015
Tan-Ya Yin	07/02/2015
Chia-Wei Huang	07/02/2015
Shu-Ru Wang	07/02/2015
Yung-Feng Cheng	07/02/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15434067

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

Address Line 1: P.O.BOX 506

PATENT

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER: NAUP2501USA1

NAME OF SUBMITTER: KATE YEH

SIGNATURE: /KATE YEH/

DATE SIGNED: 02/16/2017

Total Attachments: 28

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

SEMICONDUCTOR STRUCTURE AND METHOD OF FORMING THE SAME

As the below named inventor, I hereby declare that:

This declaration is directed to:

The attached application, or

United States application number _____ filed on _____, or

PCT international application number _____ filed on _____

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I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

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representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WINTNESS WHEREOF, I have hereunto set hand and seal this Jul 02 2015 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ching-Wen Hung**

Date: JUL 02 2015

Signature: Ching-Wen Hung

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Wei-Cyuan Lo**

Date: **JUL 02 2015**

Signature: Wei-Cyuan Lo

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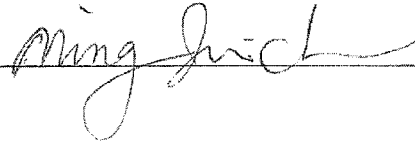
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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ming-Jui Chen**

Date: ***JUL 02 2015**

Signature:

A handwritten signature in cursive script, appearing to read "Ming Jui Chen", written over a horizontal line.

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chia-Lin Lu**

Date: **JUL 02 2015**

Signature: Chia-Lin Lu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Jia-Rong Wu**

Date: **JUL 02 2015**

Signature: Jia Rong Wu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yi-Hui Lee**

Date:

JUL 02 2015

Signature:

Yi Hui Lee

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ying-Cheng Liu**

Date: JUL 02 2015

Signature: Ying - Cheng Liu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yi-Kuan Wu**

Date: **JUL 02 2015**

Signature: Yi-Kuan Wu

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Inventor: **Chih-Sen Huang**

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Signature: Chih-Sen Huang

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Signature: Yi-Wei Chen

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I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WINTNESS WHEREOF, I have hereunto set hand and seal this JUL 02 2015 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Tan-Ya Yin**

Date: **JUL 02 2015**

Signature: Tan-Ya Yin

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

SEMICONDUCTOR STRUCTURE AND METHOD OF FORMING THE SAME

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chia-Wei Huang**

Date: JUL 02 2015

Signature: Chia-Wei Huang

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

SEMICONDUCTOR STRUCTURE AND METHOD OF FORMING THE SAME

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
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Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shu-Ru Wang**

Date: **JUL 02 2015**

Signature: Shu-Ru Wang

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

SEMICONDUCTOR STRUCTURE AND METHOD OF FORMING THE SAME

As the below named inventor, I hereby declare that:
This declaration is directed to:

The attached application, or

United States application number _____ filed on _____, or

PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

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In consideration of the payment by **UNITED MICROELECTRONICS** having a postal address of **CORP.**

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

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IN WITNESS WHEREOF, I have hereunto set hand and seal this JUL 02 2015 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yung-Feng Cheng**

Date: **JUL 02 2015**

Signature: *Yung Feng Cheng*